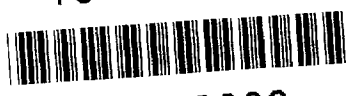




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DOCKET NO.: 2695-016 and -016A PA

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereto:

<p>1. Name of conveying party(ies): Shinichi HARADA, Kiyoshi TANBO, Sadaaki KURATA, Manabu TERAOKA, Ikuo KAKIUCHI</p> <p>Additional name(s) of conveying party(ies) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>	<p>2. Name and address of receiving party(ies): Name: <u>TAIYO YUDEN CO., LTD</u> Tokyo, Japan and <u>CHUKI SEIKI CO., LTD.</u> Wakayama, Japan</p> <p>Additional name(s) & address(es) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>
<p>3. Nature of conveyance: <input checked="" type="checkbox"/> Assignment <input type="checkbox"/> Merger <input type="checkbox"/> Security Agreement <input type="checkbox"/> Change of Name <input type="checkbox"/> Other</p> <p>Execution Date: <u>September 29, 30, October 30, 2000</u></p>	

<p>4. Application number(s) or patent number(s): If the document is being filed together with a new application, the execution date of the application is:</p> <table border="1"><tr><td>A. Patent Application No(s). Patent No. 6,070,787 and Serial No. 09/567,325</td><td>B. Patent No(s). </td></tr></table> <p>Additional numbers attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>		A. Patent Application No(s). Patent No. 6,070,787 and Serial No. 09/567,325	B. Patent No(s).
A. Patent Application No(s). Patent No. 6,070,787 and Serial No. 09/567,325	B. Patent No(s). 		

<p>5. Name and address of party to whom correspondence concerning document should be mailed: Name: <u>LOWE HAUPTMAN GOPSTEIN GILMAN & BERNER</u> Internal Address: Street Address: <u>1700 Diagonal Road, Suite 310</u> City: <u>Alexandria</u> State: <u>VA</u> ZIP: <u>22314</u></p>	<p>6. Total number of applications and patents involved: <u>2</u></p> <p>7. Total fee (37 CFR 3.41)..... <u>\$80.00</u> <input checked="" type="checkbox"/> Enclosed (credit card form for \$80.00) <input type="checkbox"/> Authorized to be charged to deposit account</p> <p>8. Deposit account number: <u>07-1337, if necessary</u></p>
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<p>9. Statement and signature. <i>To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.</i></p> <table border="1"><tr><td><u>Allan M. Lowe, Reg. No. 19,641</u> Name and Registration No. of Person Signing</td><td> Signature</td><td><u>Sept. 28, 2001</u> Date</td></tr></table> <p>Total number of pages comprising cover sheet: <u>1</u></p>		<u>Allan M. Lowe, Reg. No. 19,641</u> Name and Registration No. of Person Signing	 Signature	<u>Sept. 28, 2001</u> Date
<u>Allan M. Lowe, Reg. No. 19,641</u> Name and Registration No. of Person Signing	 Signature	<u>Sept. 28, 2001</u> Date		

CMB No. 0851-0011 (exp. 4/94)

10/04/2001 BABRAHA1 00000113 09567325
01 FC:581 80.00

Docket No. 2695-016

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

(1) Shinichi HARADA(2) Kiyoshi TANBO(3) Sadaaki KURATA(4) Manabu TERAOKA(5) Ikuo KAKIUCHI

(6) _____

who have made a certain new and useful invention, hereby sell, assign and transfer unto

TAIYO YUDEN CO. LTD., a corporation of Japan, and CHUKI SEIKI CO., LTD., a corporation of Japan

their successors and assigns (hereinafter designated "ASSIGNEES") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

METHOD OF MANUFACTURING CHIP COMPONENTS, APPARATUS FOR MANUFACTURING UNIT ELEMENTS FOR CHIP COMPONENTS, AND CHIP COMPONENT MOUNTING STRUCTURE

(a) for which an application for United States Letters Patent was filed on October 29, 1997, and identified by United States Serial No. 08/960,368 (now U.S. Patent 6,070,787) and the divisional application of United States Serial No. 08/960,368 identified by United States Serial No. 09/567,325 filed May 9, 2000

and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, substitutes, renewals, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEES, for its interest as ASSIGNEES, their successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEES;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, continuation, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEES, their successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEES' full protection and title in and to the invention hereby transferred.

SIGNED on the dates indicated aside our signatures:

INVENTORS

1) Shinichi HARADA

Name: _____

2) Kiyoshi TANBO

Name: _____

3) Sadaaki KURATA

Name: _____

4) Manabu TERAOKA

Name: _____

5) Ikuo KAKIUCHI

Name: _____

6) _____

Name: _____

DATE SIGNED

September 29, 2000September 29, 2000September 29, 2000September 30, 2000October 30, 2000